Electronic Pate	nt App	lication Fe	e i ransmit	tai			
Application Number:	105	10586335					
Filing Date:	09	09-Jan-2007					
Title of Invention:	Mu	Multilayer printed wiring board and test body for printed wiring board					
First Named Inventor/Applicant Name:	Tak	Takahiro Yamashita					
Filer:	Mai	Marvin Jay Spivak/Nina Leta					
Attorney Docket Number:	293	293627US40PCT					
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Fil	ing Fees	;					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:	'						
Pages:					<u> </u>		
Claims:							
Claims in excess of 20		1615	4	52	208		
Miscellaneous-Filing:			1				
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			208